

# H263-S64-AAN1

## DP 2U 4-Node High Density Server



### Features

- 2U 4-node rear access server system
- 4th Gen Intel® Xeon® Scalable Processors
- Intel® Xeon® CPU Max Series
- Dual processors, LGA4677
- 8-Channel RDIMM DDR5 per processor, 16 x DIMMs per node
- Supports Intel® Optane™ Persistent Memory 300 series
- Dual ROM Architecture supported
- 4 x Dedicated management ports
- 1 x CMC global management port
- 8 x 2.5" Gen4 NVMe/SATA hot-swappable bays
- 4 x M.2 with PCIe Gen4 x4 interface (optional)
- 4 x Low-profile PCIe Gen5 x16 expansion slots
- 4 x OCP 3.0 Gen5 x16 mezzanine slots
- Dual 2600W 80 PLUS Titanium redundant power supply

### Specification

|                        |  |                             |  |
|------------------------|--|-----------------------------|--|
| <b>Dimensions</b>      | 2U 4-Node - Rear access (W448 x H87.5 x D840 mm)   | <b>Rear I/O</b>             | Total: 8 x USB 3.2 Gen1, 4 x VGA, 4 x MLAN, 1 x CMC MLAN   |
| <b>Motherboard</b>     | MS63-HD1   | <b>Backplane I/O</b>        | PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s   |
| <b>CPU</b>             | 4th Generation Intel® Xeon® Scalable Processors<br>Intel® Xeon® CPU Max Series<br>Intel® Xeon® Platinum Processor, Intel® Xeon® Gold Processor,<br>Intel® Xeon® Silver Processor<br>CPU TDP up to 270W | <b>TPM</b>                  | 1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)  |
| <b>Socket</b>          | 2 x LGA 4677 (Socket E) per node   | <b>Power Supply</b>         | Dual 2600W 80 PLUS Titanium redundant power supply<br>Available for 2+1 redundant power supply configuration (optional)<br>AC Input: 100-240V  |
| <b>Chipset</b>         | Intel® C741 Chipset  | <b>System Management</b>    | Aspeed® AST2600 management controller<br>GIGABYTE Management Console (AMI MegaRAC SP-X)  |
| <b>Memory</b>          | Total 64 x DIMM slots (16 x DIMM slots per node)<br>RDIMM modules up to 128GB supported<br>3DS RDIMM modules up to 256GB supported<br>Memory speed: Up to 4800 MHz                                     | <b>OS Compatibility</b>     | Windows Server 2019 / 2011<br>RHEL 8.4 / 8.5 / 8.6 / 8.7 / 9.0 / 9.1 ( x64)<br>SLES 15 SP3 / 15 SP4 ( x64)<br>Ubuntu 22.04 LTS / 22.04.1 LTS (x64)<br>VMware ESXi 7.0 Update 3i / 8.0  |
| <b>LAN</b>             | Total: 4 x Dedicated management ports<br>1 x 10/100/1000 CMC global management port  | <b>System Fans</b>          | 4 x 80x80x80mm (16,500rpm)   |
| <b>Video</b>           | Integrated in Aspeed AST2600<br>2D Video Graphic Adapter with PCIe bus interface<br>1920x1200@60Hz 32bpp, DDR4 SDRAM<br><br>Management chip on CMC board:<br>Integrated in Aspeed AST2520A2-GP         | <b>Operating Properties</b> | Operating temperature: 10°C to 35°C<br>Operating humidity: 8-80% (non-condensing)<br>Non-operating temperature: -40°C to 60°C<br>Non-operating humidity: 20%-95% (non-condensing)  |
| <b>Storage</b>         | Total: 8 x 2.5" Gen4 NVMe/SATA hot-swappable bays<br>SAS card is required for SAS devices support  | <b>Packaging Content</b>    | 1 x H263-S64, 8 x CPU heatsinks, 1 x Rail kit, 24 x Carrier clips<br>Packaging Dimensions: 1179 x 700 x 380 mm   |
| <b>RAID</b>            | Intel® SATA RAID 0/1/10/5  | <b>Reference Numbers</b>    | Barebone package: 6NH263S64DR000AAN1*<br>- Motherboard: 9MS63HD1UR-000<br>- Rail kit: 25HB2-A66125-K0R<br>- CPU heatsink: 25ST1-453200-A0R/25ST1-453208-C1R<br>- M.2 extension riser card: 9CMTPO61NR-00 (optional)<br>- Back plane board: 9CBPH081NR-00<br>- Ring topology kit: 6NH263S62S1000AAN11 (optional, QPA:1)<br>- Power Supply: 25EPO-226000-G1S<br>- C19 power cord 125V/15A (US): 25CP1-018000-Q0R (optional)<br>- C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional) |
| <b>Expansion Slots</b> | Total:<br>4 x PCIe Gen5 x16 low-profile slots<br>4 x OCP 3.0 Gen5 x16 mezzanine slots<br>*4 x M.2 slots (M-key, PCIe Gen4 x4, NGFF-2280/22110)<br><br>*Optional kit for M.2 extension riser card       |                             |  |



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